

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	3509650
<b>Application Number:</b>	10757770
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	5493
<b>Title of Invention:</b>	Limited thermal budget formation of PMD layers
<b>First Named Inventor/Applicant Name:</b>	Zheng Yuan
<b>Customer Number:</b>	57385
<b>Filer:</b>	Eugene Jerome Bernard/Cindy Keefe
<b>Filer Authorized By:</b>	Eugene Jerome Bernard
<b>Attorney Docket Number:</b>	A7443.P1/T52200
<b>Receipt Date:</b>	24-JUN-2008
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<b>Application Type:</b>	Utility under 35 USC 111(a)

### Payment information:

Submitted with Payment	no
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### File Listing:

Document Number	Document Description	File Name	File Size(Bytes) /Message Digest	Multi Part /.zip	Pages (if appl.)
1		3rd_SIDS_w_RCE_016301_052200US_61407212_1.pdf	249044 7f944234cefdc3d6a53cfae5887590eb59907d2f	yes	9

	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Information Disclosure Statement Letter		1	2	
	Information Disclosure Statement (IDS) Filed		3	9	
Warnings:					
Information:					
2	Foreign Reference	CA479107.pdf	1516933	no	28
			6d2f22d0a79617644c2b5ab8ec5f5b241ebf61a8		
Warnings:					
Information:					
3	Foreign Reference	EP0520519.pdf	2503701	no	34
			bc8e26e4f3cde4719d5445a44c4986e0b6b732b4		
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4	Foreign Reference	JP_1294868_Engabstract.pdf	95851	no	2
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Information:					
5	Foreign Reference	JP_1283375_Engabstract.pdf	82481	no	1
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6	Foreign Reference	JP4154116.pdf	702119	no	13
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7	Foreign Reference	JP_11176593_Engabstract.pdf	157306	no	2
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8	Foreign Reference	TW479315B.pdf	395393	no	6
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9	Foreign Reference	WO9925895.pdf	2845108	no	57
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10	NPL Documents	SACVD_Applied_Materials_website.pdf	90139	no	2
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11	NPL Documents	BAKER_STI_TEOS_densification.pdf	435857	no	7
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12	NPL Documents	Bang_et_al.pdf	640392	no	9
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13	NPL Documents	Furnace_definitions.pdf	55458	no	1
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14	NPL Documents	Fujino_DependenceofDeposition.pdf	445791	no	5
			762140de9a012abd19f5a6ccece08a1a9b89225		
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15	NPL Documents	Kuo_EtchMechanism.pdf	268855	no	3
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16	NPL Documents	Kwok-P2172-Surface_Related-J_Electrochem_Soc-V141-N8-1994.pdf	602975	no	6
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17	NPL Documents	Lassig-Intermetal_Dielectric_Deposition.pdf	928472	no	22
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18	NPL Documents	Li_ModelingStudies.pdf	159642	no	3
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19	NPL Documents	Machida-P818-Si02-J_Vac_Sci_Technol_B-V4-N4-1986.pdf	382854	no	4
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Information:					
Total Files Size (in bytes):			12558371		
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p><u>New International Application Filed with the USPTO as a Receiving Office</u> If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>					